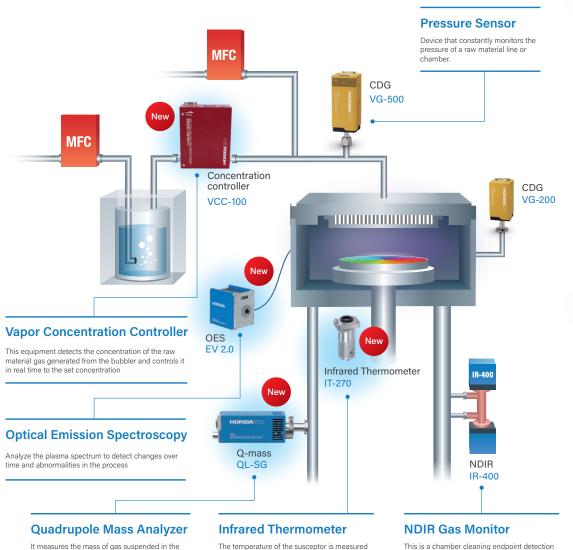
## Chamber Health Monitoring





from outside the chamber through a window in

a non-contact manner to control the wafer

temperature

chamber after chamber opening and before the

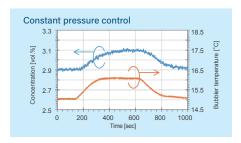
process to monitor the chamber condition

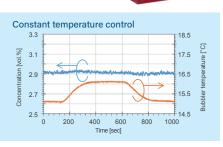
Stabilize amount of row material generated from bubbler and stabilize the quality

Integration of NDIR technology cultivated in IR-300 series and HORIBA's pressure control technology

## **▶ VCC-100**

- Compact design
- Temperature control with a single unit
- Temperature control mode and pressure control mode are selectable





Measured residual gas in the chamber during start-up after maintenance or before starting the process

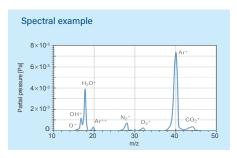
Compact design that can be installed around the chamber and the sensor can be replaced by the user

## **QL-SG**

monitor for the deposition process that

monitors exhaust gas components (SiF<sub>4</sub>, CF<sub>4</sub>)

- User replaceable sensor
- High maximum operating pressure 0.5 Pa (for 1-65 AMU sensor)
- Selectable from Y2O3/Ir, Re/W filaments







## Changes in residual gas components before and after baking

